

ABSTRACT OF THE DISCLOSURE

A structure for a micro-device is fabricated by forming: a first layer of sacrificial material, a layer of structural material over the first sacrificial material layer, a second layer of sacrificial material over the structural material layer and a protective layer over the second sacrificial material layer. A release etch is used to remove the first and second sacrificial material layers at approximately the same rate. A structural feature may also be fabricated by forming: a first layer of a first material; a layer of structural material over the first layer of the first material; at least one cut in the structural material layer; and, a first layer of a sacrificial material, different from the first material, over the structural material layer such that an interface is created between the first layer of the sacrificial material and the first layer of the first material at the at least one cut.

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